

Two chip fabrication plants to come up in India: MoS IT

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Two full-fledged semiconductor fabrication plants are going to come up very soon entailing multi-billion dollar investment besides several chip assembly and packaging units, Minister of Electronics and IT Rajeew Chandrasekhar said.

In an interview with *PTI*, the minister confirmed that the two projects include a \$8 billion proposal submitted by Israel-based Tower Semiconductors and the other from Tata Group.

“I am happy to share this with you and you are probably the first one I’m sharing this with. In the near term, two full-blown fabs are going to come up in India. These are going to be multi-billion-dollar fabs in the 65, 40 and 28-nanometer technology and there are going to be a host of other packaging proposals that we are

evaluating,” Chandrasekhar said.

He was responding to a question on \$8 billion investment proposal submitted by Tower Semiconductors and the status of India’s semiconductor road map. The minister said that the project will be approved in the third term of Prime Minister Narendra Modi if they are not cleared before the upcoming general elections. The government has received four proposals for setting up semiconductor manufacturing plants and 13 for chip assembly, testing, monitoring and packaging (ATMP) units.

